

PCN Number:	20190517000.1A	PCN Date:	May 28, 2019						
Title:	Qualify New Assembly Material set for Selected Device(s)								
Customer Contact:	PCN Manager	Dept:	Quality Services						
Proposed 1st Ship Date:	Aug 20, 2019	Estimated Sample Availability:	Date provided at sample request						
Change Type:									
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design						
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet						
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change						
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site						
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process						
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site						
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material						
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process						
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site						
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials						
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process						
PCN Details									
Description of Change:									
<p>Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification. These additional devices are in bold highlight below. The expected first shipment date for these new devices will be 90 days from this notice for these newly added devices only.</p> <p>Texas Instruments is pleased to announce the qualification of new assembly material set for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:</p>									
<table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Material</th> <th>Current</th> <th>Proposed</th> </tr> </thead> <tbody> <tr> <td>Mold compound</td> <td>31252002-0</td> <td>31125011-0</td> </tr> </tbody> </table>				Material	Current	Proposed	Mold compound	31252002-0	31125011-0
Material	Current	Proposed							
Mold compound	31252002-0	31125011-0							
Reason for Change:									
Continuity of supply. Mold compound supplier (Shinetsu) decided to end of life part no. 31252002-0 mold compound									
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):									
None.									
Anticipated impact on Material Declaration									
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.						
Changes to product identification resulting from this PCN:									
None									
Product Affected:									
LM3S1133-IQC50-A2	LM3S1918-IQC50-A2	LM3S2965-IBZ50-A2	LM3S6938-IQC50-A2						
LM3S1133-IQC50-A2T	LM3S1918-IQC50-A2T	LM3S2965-IQC50-A2	LM3S6938-IQC50-A2T						
LM3S1138-IBZ50-A2T	LM3S1937-IQC50-A2	LM3S2965-IQC50-A2T	LM3S6950-IQC50-A2						
LM3S1138-IQC50-A2	LM3S1958-IQC50-A2	LM3S6100-IQC25-A2	LM3S6950-IQC50-A2T						
LM3S1138-IQC50-A2T	LM3S1960-IQC50-A2	LM3S6100-IQC25-A2T	LM3S6952-IQC50-A2						
LM3S1150-IQC50-A2	LM3S1968-IBZ50-A2	LM3S6432-IBZ50-A2	LM3S6965-EQC50-A2						
LM3S1162-IQC50-A2	LM3S1968-IBZ50-A2T	LM3S6432-IBZ50-A2T	LM3S6965-IBZ50-A2						
LM3S1162-IQC50-A2T	LM3S1968-IQC50-A2	LM3S6432-IQC50-A2	LM3S6965-IQC50-A2						

LM3S1165-IQC50-A2	LM3S1968-IQC50-A2T	LM3S6432-IQC50-A2T	LM3S6965-IQC50-A2T
LM3S1165-IQC50-A2T	LM3S2016-IQC50-A2	LM3S6537-IQC50-A2	LM3S8530-IBZ50-A2
LM3S1332-IQC50-A2	LM3S2110-EQC25-A2	LM3S6610-IQC25-A2	LM3S8530-IBZ50-A2T
LM3S1439-IQC50-A2	LM3S2110-IQC25-A2	LM3S6611-IBZ50-A2	LM3S8530-IQC50-A2
LM3S1512-IQC25-A2	LM3S2139-IQC25-A2	LM3S6611-IQC50-A2	LM3S8738-IQC50-A2
LM3S1538-IQC50-A2	LM3S2139-IQC25-A2T	LM3S6618-IQC50-A2	LM3S8738-IQC50-A2T
LM3S1601-IQC50-A2	LM3S2412-IQC25-A2	LM3S6730-IQC50-A2	LM3S8930-IQC50-A2
LM3S1601-IQC50-A2T	LM3S2601-IQC50-A2	LM3S6730-IQC50-A2T	LM3S8933-IQC50-A2
LM3S1608-IQC50-A2	LM3S2608-IQC50-A2	LM3S6753-IQC50-A2	LM3S8938-EQC50-A2
LM3S1608-IQC50-A2T	LM3S2608-IQC50-A2T	LM3S6911-IBZ50-A2	LM3S8938-IBZ50-A2
LM3S1635-IQC50-A2	LM3S2620-IQC25-A2	LM3S6911-IBZ50-A2T	LM3S8938-IQC50-A2
LM3S1637-IQC50-A2	LM3S2651-IQC50-A2	LM3S6911-IQC50-A2	LM3S8938-IQC50-A2T
LM3S1751-IBZ50-A2	LM3S2651-IQC50-A2T	LM3S6911-IQC50-A2T	LM3S8962-EQC50-A2
LM3S1751-IQC50-A2	LM3S2739-IQC50-A2	LM3S6915-IBZ50-A2	LM3S8962-IBZ50-A2
LM3S1911-IBZ50-A2T	LM3S2911-IQC50-A2	LM3S6915-IQC50-A2	LM3S8962-IQC50-A2
LM3S1911-IQC50-A2	LM3S2918-IQC50-A2	LM3S6916-IQC50-A2	LM3S8962-IQC50-A2T
LM3S1911-IQC50-A2T	LM3S2948-EQC50-A2	LM3S6918-EQC50-A2	LM3S8970-IQC50-A2
LM3S1918-EQC50-A2	LM3S2948-IQC50-A2	LM3S6918-IBZ50-A2	LM3S8970-IQC50-A2T
LM3S1918-EQC50-A2T	LM3S2950-IQC50-A2	LM3S6918-IQC50-A2	LM3S8971-IQC50-A2
LM3S1918-IBZ50-A2	LM3S2965-EQC50-A2	LM3S6918-IQC50-A2T	LM3SA000-IQC50-A2T

Qualification Report

Approve Date 14-May-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>LM3S1XXX-IBZ50-A2T</u> (SINGLE DIE)	Qual Device: <u>LMS6XXX-IBZ50-A2</u> (STACKED DIE)
PC	Preconditioning	MSL3/260C	1/77/0	1/154/0
TC	Temperature cycling - 55C/125C	700 cycles	1/66/0	1/71/0
UHAST	Unbiased HAST	110C/85%RH/17.7 psis (264 Hours)	-	1/72/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass

- Device LMS6XXX-IBZ50-A2 (STACKED DIE) contains multiple dies.
 - Preconditioning was performed for Unbiased HAST, Temperature Cycle
 - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their

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